



## CAHILL, SUTTON & THOMAS P.L.C. 155 Park One 2141 East Highland Avenue Phoenix, Arizona 85016 Ph. (602) 956-7000 Fax (602) 495-9475

Date: March 21, 2002 Docket No. 5833-A-13

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231 on: March 21, 2002

Marvin A. Glazer

Name of Registered Rep.

Signature

<u>March 21, 200</u>2 Date

**EXAMINER:** 

NGUYEN, THINH T.

**ART UNIT:** 

2818

**APPLICANTS:** 

JAMIN LING, ET AL.

**SERIAL NO.:** 

09/766,798

FILED:

Jan. 22, 2001

FOR:

"ELECTROLESS Ni/Pd/Au METALLIZATION STRUCTURE

FOR COPPER INTERCONNECT SUBSTRATE AND METHOD

THEREFOR"

Honorable Commissioner for Patents Washington, D.C. 20231

Sir:

Transmitted herewith is an Amendment, with a clean copy of the claims attached thereto as Attachment A, in the above-identified application.

The fee has been calculated as shown below:

## **CLAIMS AS AMENDED**

	Claims	
	Remaining	Highest No.
	After	Previously Present Additional
	Amendment	Paid For Extra Fee
Total Claims Indep.	22 minus	= x \$18.000
Claims	2 minus	$\underline{}$ = $\underline{}$ x \$84.00 $\underline{}$ -0-

Total Additional Fee For This Amendment: \_\_-0-\_

- X A check in the amount of \$110.00 is attached (extension fee).
- X Please charge any additional fees or credit overpayment to Deposit Account No. 03-0088. Two (2) duplicate copies of this sheet are enclosed.
- X A Petition for One-Month Extension of Time is enclosed.
- X A Request for Entry of Formal Drawings is enclosed, along with one sheet of formal drawings.

Marvin A. Glazer

Reg. No. 28,801



7	IN THE UNITED STATES PATENT AND TRADEMARK OFFICE			
2	EXAMINER: NGUYEN, THINH T.  APPLICANTS: JAMIN LING, ET AL.  SERIAL NO.: 09/766,798  FILED: Jan. 22, 2001  FOR: "ELECTROLESS Ni/Pd/Au METALLIZATION STRUCTURE FOR COPPER INTERCONNECT SUBSTRATE AND METHOD THEREFOR"			
3	APPLICANTS: JAMIN LING, ET AL.  SERIAL NO.: 09/766,798  THE PROPERTY OF THE PR			
4	SERIAL NO.: 09/766,798			
5	FILED: Jan. 22, 2001			
6	FOR: "ELECTROLESS Ni/Pd/Au METALLIZATION ) STRUCTURE FOR COPPER INTERCONNECT )			
7	SUBSTRATE AND METHOD THEREFOR"			
8	I hereby certify that this correspondence is being deposited with the United			
9	States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231 on: March 21, 2002			
10	Marvin A. Glazer Name of Registered Repa			
11	Marina Rail March 21, 2002 AMark			
12	Signature Date			
13	REQUEST FOR ENTRY OF FORMAL DRAWINGS			
14	Commissioner for Patents			
15	Washington, D.C. 20231			
16	Sir:			
17	The Office Action mailed December 5, 2001, for the above-identified patent application			
18	requested the submission of formal drawings to replace the informal drawings originally filed in the application. Accordingly, please find enclosed one sheet of formal drawings to replace the			
19	informal drawings originally filed in this application.			
20	An Amendment is being submitted to the Patent Office concurrently herewith.  The Serial No., filing date, and Art Unit have been printed upon the back of the enclosed			
21	sheet adjacent the upper margins thereof.			
22	Please enter the accompanying formal drawings into the present application.			
23	Respectfully submitted,			
24	CAHILL, SUTTON & THOMAS, P.L.C.			
25	Marvin Cettas			
26	Marvin A. Glazer () Reg. No. 28,801			
27	155 Park One 2141 East Highland Avenue			
28	Phoenix, Arizona 85016 Ph. (602) 956-7000			
	Fax (602) 495-9475 5833-A-13			

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